FINISAR

PCN Number: 1266552
Date Issued: 1/18/17

Info-Note

Manufacturing Change for Specific TIA and LDPA ICs Used in Certain Finisar Transceivers and AOCs

Scope of Notification

This Info-Note outlines the changes Finisar implemented for its Trans-Impedance Amplifier (TIA) Integrated Circuit (IC) 10GTIA9x, and Laser-Driver-Post-Amplifier (LDPA) IC 8GLDPA5x used in Finisar's transceivers and Active Optical Cables (AOC) listed below.

The changes were initiated upon request of Finisar's IC Contract Manufacturer (CM), in order to transition these ICs from multi- to single-layer reticle wafers.

Affected Products and Part Numbers

The following table provide the list of Finisar's products and part numbers (P/Ns) affected by this change notification:

Finisar P/N	Product Description	IC Change
FTLF1326P3xxxxxx	SFP+: 6G, 10km, 1310nm Fabry-Perot TX and PIN RX	TIA
FTLF1426P2xxxxxx	SFP+: 6G, 10km, 1310nm DFB TX and PIN RX	TIA, LDPA
FTLF1428P2BNVxxx	SFP+: 8G, 10km, 1310nm DFB TX and PIN RX	TIA, LDPA
FTLF8528P2BNVxxx	SFP+: 8G, 150m, 850nm VCSEL TX and PIN RX	LDPA
FTLX1370D3xxxxxx	SFP+: 10G, 1.2km 1310nm Fabry-Perot TX and PIN RX	TIA
FTLX1371D3xxxxxx	SFP+: 10G, 220m, 1310nm Fabry-Perot TX and PIN RX	LDPA
FTLX1374D3xxxxxx	SFP+: 10G, 1km 1310nm Fabry-Perot TX and PIN RX	TIA
FTLX1471D3xxxxxx	SFP+: 10G, 10km 1310nm DFB TX and PIN RX	TIA, LDPA
FTLX1472x3xxxxxx	SFP+: 10G, 10km 1310nm DFB TX and PIN RX	TIA
FTLX1413M3xxxxxx	XFP: 10G, 10km 1310nm DFB TX and PIN RX	TIA
FTLX1442E2xxxxxx	X2: 10G, 10km 1310nm DFB TX and PIN RX	TIA
FTLX1462E2xxxxxx	XENPAK: 10G, 10km 1310nm DFB TX and PIN RX	TIA
FTLX2071D3xxxxxx	SFP+: 10G, 10km 1310nm Bi-Di DFB TX and PIN RX	TIA
FTLX2471D3xxxxxx	SFP+: 10G, 10km 1310nm DFB TX and PIN RX	TIA, LDPA
FTLX1672x3xxxxxx	SFP+: 10G, 40km 1550nm EML TX and PIN RX	TIA
FCBG110SD1Cxxxxx	SFP+ AOC: 10G, 30m, 850nm VCSEL TX and PIN RX	TIA
FCBN510QE2xxxxxx	QSFP AOC: 40G, 30m, 850nm VCSEL TX and PIN RX	TIA
FTLX8570D3xxxxxx	SFP+: 10G, 100m, 850nm VCSEL TX and PIN RX	LDPA
FTLX8571D3xxxxxx	SFP+: 10G, 300m, 850nm VCSEL TX and PIN RX	LDPA
FTLX8572D3xxxxxx	SFP+: 10G, 150m, 850nm VCSEL TX and PIN RX	LDPA

Reason for the Change

The production of Finisar 10G products has reached unprecedented large volumes. In order to ensure capacity expansion and continuity of supply, Finisar IC CM requested to transition these TIA and LDPA ICs from Multi- to Single-Layer Reticle (MLR to SLR) wafers, to align the manufacturing processes of these wafers to the standard production flow.

Detailed Description of Change

Along with the MLR to SLR wafer transition, a metal mask change was implemented for both the TIA and the LDPA ICs in order to:

TIA: 10GTIA9C	LDPA: 8GLDPA5B
Reduce the resistance between the V_{CC} IC input pins and the V_{CC} IC filter inputs.	Reduce the series parasitic resistance between the Post Amplifier pad and the Photo Diode monitor circuit.

Reliability and Performance Tests

Qualification tests at IC level and characterization tests at module level were carried out to guarantee that performance and reliability are per Finisar's standards.
Reports will be available upon request.

Implementation Date

In order to avoid supply disruption to our customers, Finisar will deploy the new revisions of these TIA and LDPA ICs into the products listed above as soon as it becomes necessary.

Additional Information

For more information, please contact your local Finisar representative, or

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